Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	195	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:45
L2	139	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:46
L3	8	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack) same (active or source or drain or source/drain) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:48
L4	2	(interlayer or interlevel or ild) same (slot or slit) same (gate near stack) same (active or source or drain or source/drain) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:48 ·
L5	9	(interlayer or interlevel or ild) same (slot or slit) same (gate near stack) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L6	3284	contactless and (slot or slit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L7	337	contactless and ((dimension or dimensional or width or length) near5 (slot or slit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L8	64	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L9	50	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:52

L10	11	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:53
L11	66	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L12 ·	3	contactless same ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L13	0	contactless same ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L14	40	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L15	15	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L16	8	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L17	8	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:55
L18	0	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM <u>*</u> TDB	OR	ON	2007/12/05 11:55

L19	0	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) with (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L20	i	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) same (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L21	1	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) same (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L22	1	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:57
L23	14	((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:59
L24	19	"5734607"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:00

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Page 3

L25	14	("20020038911" "5091326" "5734 607" "5734607" "6107670" "6197 639" "6495467" "6765258").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L26	1	I25 and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:02
L27	7	l25 and (slot or slit or via or opening or hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:02
L28	3	I25 and ((bit or bitline) near10 (slot or slit or via or opening or hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L29	3	I25 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L30	15	("20020038911" "5091326" "5734 607" "5734607" "6107670" "6197 639" "6495467" "6765258").PN. or 10/751193	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L31	4	I30 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:04
L32	2	l30 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless) with (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06
L33	3	I30 and ((bit or bitline) with (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06

L34	3	I30 and ((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06
L35	1	I30 and ((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:07
L36	2106	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:07
L37	618	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:08
L38	<b>289</b>	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:08

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L39	302	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimensional or dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:09
L40	189	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimensional or dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate and ((slot or slit or via or opening or hole) near10 (resist or photoresist or lithography or photolithography or image or imaging or imaged))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:10
L61	20311	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:16
L62	1037	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17

L63	677	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or opening or hole or via) with (bit or bitline or bit-line) with (insulating or dielectric or ild or insulation or interlayer or inter-layer or interlevel or inter-level)) same (active or source or drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17
L64	551	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 438/261. ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.cc	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17
L65	107	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) with (bit or bitline or bit-line) with (insulating or dielectric or ild or insulation or interlayer or inter-layer or interlevel or inter-level)) with (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:18

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L66	293	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or intercept or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:19
L67	159	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103.ccls. or 438/128.ccls. or 438/129.ccls. or 438/257.ccls. or 438/261.ccls. or 438/263.ccls. or 438/197.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography) or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:20

257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/290.ccls. or 257/E21.682.ccls. or 257/E27.103.ccls. or 438/128.ccls. or 438/129.ccls. or 438/257.ccls. or 438/261.ccls. or 438/263.ccls. or 438/197.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same bit or bitline or bit-line) same insulating or dielectric or ild or nesulation or interlayer or inter-layer or inter-layer or inter-level) same (active or ource or drain) and ((dimension or dimensional or length or width) sear10 (slit or slot or opening or sole or via)) and ((slot or via or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:22
pening or slit or hole) near10 image or imaging or lithography or photolithography)) and ((slot or lit or via or opening or hole) lear10 (contact or contactless))				
257/314.ccls. or 257/315.ccls. or 57/316.ccls. or 257/317.ccls. or 57/390.ccls. or 257/391.ccls. or 57/291.ccls. or 257/291.ccls. or 257/E21.682.ccls. or 257/E27.103.cls. or 438/128.ccls. or 438/129.cls. or 438/257.ccls. or 438/261.cls. or 438/263.ccls. or 438/197.cls. or 365/185.01.ccls. or 65/185.33.ccls.) and ((slot or slit r opening or hole or via) same bit or bitline or bit-line) same insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level or ource or drain) and ((dimension r dimensional or length or width) ear10 (slit or slot or opening or ole or via)) and ((slot or via or pening or slit or hole) near10 mage or imaging or imaged or esist or photoresist or lithography r photolithography) and ((slot or via or photolithography)) and (slot or via or photolithography)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:25
nsi ou r c ea ole pe im:	ulation or interlayer or er-layer or interlevel or er-level)) same (active or irce or drain) and ((dimension dimensional or length or width) ir10 (slit or slot or opening or e or via)) and ((slot or via or ening or slit or hole) near10 age or imaging or imaged or	ulation or interlayer or er-layer or interlevel or er-layer or interlevel or er-level)) same (active or irce or drain) and ((dimension dimensional or length or width) ir10 (slit or slot or opening or e or via)) and ((slot or via or ening or slit or hole) near10 age or imaging or imaged or st or photoresist or lithography photolithography)) and ((slot or or via or opening or hole) ir10 (contact or contactless)	ulation or interlayer or er-layer or interlevel or er-level)) same (active or irce or drain) and ((dimension dimensional or length or width) ir10 (slit or slot or opening or e or via)) and ((slot or via or ening or slit or hole) near10 age or imaging or imaged or st or photoresist or lithography photolithography)) and ((slot or or via or opening or hole) ir10 (contact or contactless)	ulation or interlayer or er-layer or interlevel or er-level)) same (active or irce or drain) and ((dimension dimensional or length or width) ir10 (slit or slot or opening or e or via)) and ((slot or via or ening or slit or hole) near10 age or imaging or imaged or st or photoresist or lithography photolithography)) and ((slot or or via or opening or hole) ir10 (contact or contactless)

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L70  76  (257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole) near10 gate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:25

171	07	/257/214 cele en 257/215 cele en	LIC DCDLID	OD	ON	2007/12/05 12:26
L71	87	(257/314.ccls. or 257/315.ccls. or	US-PGPUB;	OR	ON	2007/12/05 12:26
		257/316.ccls. or 257/317.ccls. or	USPAT;		İ	
		257/390.ccls. or 257/391.ccls. or	EPO; JPO; DERWENT;			
		257/E21.682.ccls. or 257/E27.103.	IBM_TDB			
		ccls. or 438/128.ccls. or 438/129.	ם מו"ו ויום ו			
		ccls. or 438/257.ccls. or 438/261.				
		ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or			ļ	
		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
		(bit or bitline or bit-line) same				
		(insulating or dielectric or ild or				
		insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				
		slit or via or opening or hole)				
		near10 (contact or contactless)				
		near10 (bit or bitline or bit-line))				
		and ((slot or slit or opening or				
		hole or via) near10 gate)				

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L72	45	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:27
		ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or				
		insulation or interlayer or inter-layer or inter-level or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole)				
		near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate)				

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173		(257/214l 257/215	LIC DCDUS	00	ON	2007/12/05 12 20
L73	7	(257/314.ccls. or 257/315.ccls. or	US-PGPUB;	OR	ON	2007/12/05 12:28
		257/316.ccls. or 257/317.ccls. or	USPAT;			
		257/390.ccls. or 257/391.ccls. or	EPO; JPO;	ļ		
		257/E21.682.ccls. or 257/E27.103.	DERWENT;			
		ccls. or 438/128.ccls. or 438/129.	IBM_TDB			
		ccls. or 438/257.ccls. or 438/261.				
		ccls. or 438/263.ccls. or 438/197.				
		ccls. or 365/185.01.ccls. or				
	ļ	365/185.33.ccls.) and ((slot or slit or opening or hole or via) same				
		(bit or bitline or bit-line) same				
		(insulating or dielectric or ild or				
		insulating of dielectric of hid of				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or		`		
		slit or via or opening or hole)				
		near10 (contact or contactless)				
		near10 (bit or bitline or bit-line))				
		and ((slot or slit or opening or				
		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate) and ((slot or slit or hole or				
		opening or via) near10 (dimension				
		or dimensional))				

L74	1	(257/314 cels, or 257/315 cels, or	US-PGPUB;	OR	ON	2007/12/05 12:29
L/7	1	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or	USPAT;	J OK	ON	2007/12/05 12:29
		257/390.ccls. or 257/391.ccls. or	EPO; JPO;			
		257/E21.682.ccls. or 257/E27.103.	DERWENT;			
		ccls. or 438/128.ccls. or 438/129.	IBM_TDB			
		ccls. or 438/257.ccls. or 438/261.	15.150			
		ccls. or 438/263.ccls. or 438/197.				
		ccls. or 365/185.01.ccls. or				
		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
		(bit or bitline or bit-line) same				,
		(insulating or dielectric or ild or				
		insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
Ì	•	opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				·
		slit or via or opening or hole)				
		near10 (contact or contactless)				
		near10 (bit or bitline or bit-line))				
•	•	and ((slot or slit or opening or				
,		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate) and ((slot or slit or hole or		•		
		opening or via) near10 (dimension or dimensional)) and contactless				
		or dimensionary) and contactiess				

			Γ		<del></del>	
L75	4	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-layer or inter-layer or or inter-layer or interlevel or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or slit or opening or hole) near10 (slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:29

176	24	(257/214 colo en 257/215 colo en	LIC DCDLID	00	ON	2007/12/05 12:20
L76	24	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or	US-PGPUB; USPAT;	OR	ON	2007/12/05 12:30
		257/390.ccls. or 257/391.ccls. or	EPO; JPO;			
		257/E21.682.ccls. or 257/E27.103.	DERWENT;			
		ccls. or 438/128.ccls. or 438/129.	IBM_TDB			
		ccls. or 438/257.ccls. or 438/261.	1011_100			
		ccls. or 438/263.ccls. or 438/197.				
		ccls. or 365/185.01.ccls. or				
		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
		(bit or bitline or bit-line) same		İ		
		(insulating or dielectric or ild or				
		insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				,
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				
		slit or via or opening or hole)				
		near10 (contact or contactless)				
		near10 (bit or bitline or bit-line))				
		and ((slot or slit or opening or				
		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate) and (contactless or (contact				
		near10 (without or simultaneous or time)))				
		Or time)))				

L78	34	(257/314.ccls. or 257/315.ccls. or	US-PGPUB;	OR	ON	2007/12/05 12:33
L/6	34	257/314.ccls. or 257/313.ccls. or 257/317.ccls. or	USPAT;		ON	200//12/05 12.55
		257/390.ccls. or 257/391.ccls. or	EPO; JPO;			
		257/E21.682.ccls. or 257/E27.103.	DERWENT;			
ł		ccls. or 438/128.ccls. or 438/129.	IBM_TDB			
ŀ		ccls. or 438/257.ccls. or 438/261.	15/1_/55			
		ccls. or 438/263.ccls. or 438/197.				
		ccls. or 365/185.01.ccls. or				
İ		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
İ		(bit or bitline or bit-line) same				
		(insulating or dielectric or ild or				
	•	insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
ļ		(image or imaging or imaged or				<b>'</b>
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				
İ		slit or via or opening or hole)	•			
		near10 (contact or contactless)				
}		near10 (bit or bitline or bit-line))				
		and ((slot or slit or opening or				
		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate) and ((self near (align or				
		aligning or aligned or alignment))				
		or contactless or (contact near10				
		(without or simultaneous or time				
		or simultaneously)))				